**Product data sheet** 

## 1. General description

Silicon Carbide Schottky diode in a DFN 8\*8 plastic package, designed for high frequency switched-mode power supplies.



### 2. Features and benefits

- New 6th Generation Technology
- Low Forward Voltage Drop
- Low Reverse Leakage Current
- High Forward Surge Capability I<sub>FSM</sub>
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant

## 3. Applications

- · Power factor correction
- · Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives

## 4. Quick reference data

### Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes		Values		Unit		
Absolute	Absolute maximum rating								
$V_{RRM}$	repetitive peak reverse 650 voltage				V				
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5 ; square-wave pulse; T <sub>c</sub> ≤ 153 °C; Fig. 1; Fig. 2; Fig. 3		10		А			
$T_j$	junction temperature			-55 to 175		°C			
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit		
Static ch	aracteristics								
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 10 A; T <sub>j</sub> = 25 °C; <u>Fig. 5</u>		-	1.29	1.45	V		
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 150 °C; <u>Fig. 5</u>		-	1.45	1.65	V		
Dynamic	Dynamic characteristics								
$Q_r$	recovered charge	$I_F = 10 \text{ A}$ ; $dI_F/dt = 500 \text{ A/}\mu\text{s}$ ; $V_R = 400 \text{ V}$ ; $T_j = 25 ^{\circ}\text{C}$ ; Fig. 7		-	24	-	nC		

# 5. Pinning information

### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	n.c.	not connected	[]	K <del>    </del> A
2	n.c.	not connected	5	001aaa020
3	А	anode		
4	А	anode	8	
5	К	mounting base; connected to cathode	1 2 3 4	

# 6. Ordering information

### **Table 3. Ordering information**

•	Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
١	WNSC6D10650T	DFN8*8	WNSC6D10650T6J	Таре	3000	DFN8X8N	25-Dec-2019

# 7. Marking

### Table 4. Marking codes

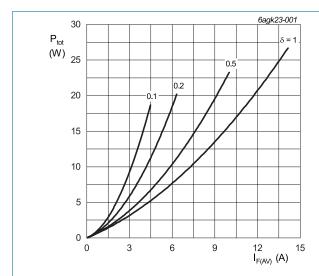
Type number	Marking codes
WNSC6D10650T	WNSC6D
	10650T

# 8. Limiting values

#### **Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage			650	V
$V_{RWM}$	crest working reverse voltage			650	V
$V_R$	reverse voltage	DC		650	V
$I_{F(AV)}$	average forward current	$\delta$ = 0.5; square-wave pulse; $T_c \le 153$ °C; Fig. 1; Fig. 2; Fig. 3		10	A
I <sub>FRM</sub>	repetitive peak forward current	$\delta$ = 0.5; t <sub>p</sub> = 25 μs; T <sub>c</sub> ≤ 153 °C; square-wave pulse		20	А
I <sub>FSM</sub>	non-repetitive peak	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse		75	Α
	forward current	$t_p = 10 \mu s; T_{j(init)} = 25 °C; square-wave pulse$		800	Α
l <sup>2</sup> t	I <sup>2</sup> t for fusing	sine-wave pulse; $T_{j(init)} = 25 \text{ °C}$ ; $t_p = 10 \text{ ms}$		28.125	A <sup>2</sup> s
T <sub>stg</sub>	storage temperature			-55 to 175	°C
T <sub>j</sub>	junction temperature			-55 to 175	°C



$$\begin{split} I_{F(AV)} &= I_{F(RMS)} \times \sqrt{\delta} \\ V_o &= 0.829 \text{ V; } R_s = 0.0748 \text{ } \Omega \end{split}$$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

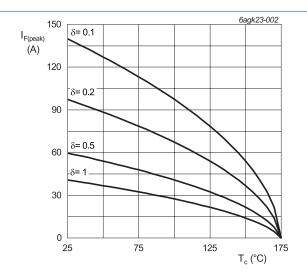
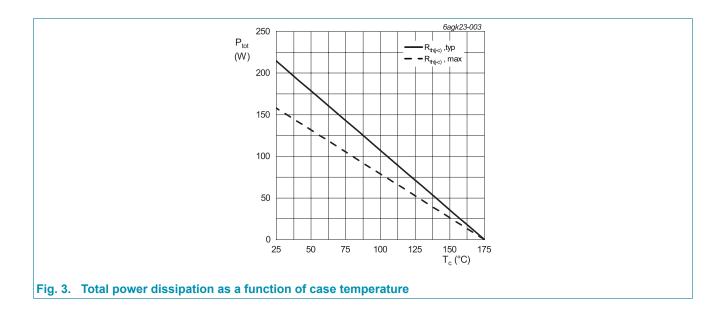


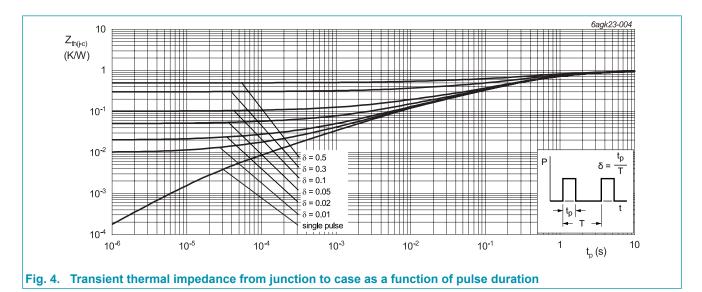
Fig. 2. Current derating as a function of case temperature



## 9. Thermal characteristics

**Table 6. Thermal characteristics** 

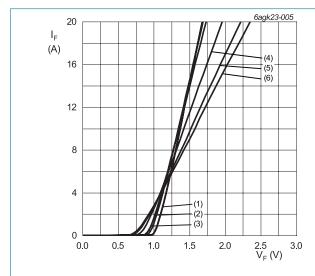
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
R <sub>th(j-c)</sub>	thermal resistance from junction to case	Fig. 4		-	0.7	0.95	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient free air	in free air		-	60	-	K/W



## 10. Characteristics

**Table 7. Characteristics** 

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit	
Static cha	Static characteristics							
$V_{F}$	forward current	I <sub>F</sub> = 10 A; T <sub>j</sub> = 25 °C; <u>Fig. 5</u>		-	1.29	1.45	V	
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 150 °C; <u>Fig. 5</u>		-	1.45	1.65	V	
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 175 °C; <u>Fig. 5</u>		-	1.50	1.70	V	
I <sub>R</sub>	reverse current	V <sub>R</sub> = 650 V; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>		-	1	50	μA	
		V <sub>R</sub> = 650 V; T <sub>j</sub> = 175 °C; <u>Fig. 6</u>		-	15	200	μA	
Dynamic	characteristics							
Q <sub>r</sub>	recovered charge	$I_F = 10 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$		-	24	-	nC	
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 1 V; T <sub>j</sub> = 25 °C		-	500	-	pF	
		f = 1 MHz; V <sub>R</sub> = 300 V; T <sub>j</sub> = 25 °C		-	58	-	pF	
		f = 1 MHz; V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C		-	52	-	pF	
E <sub>as</sub>	non-repetitive avalanche energy	$I_R = 5 \text{ A}; L = 5 \text{ mH}; T_{j(init)} = 25 \text{ °C}$		60	-	-	mJ	



 $V_o = 0.829 \text{ V}; R_s = 0.0748 \Omega$ 

(1)  $T_j = -55$  °C; typical values (2)  $T_j = 0$  °C; typical values

(3) T<sub>i</sub> = 25 °C; typical values

(4) T<sub>i</sub> = 100 °C; typical values

(5) T<sub>i</sub> = 150 °C; typical values

(6) T<sub>i</sub> = 175 °C; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

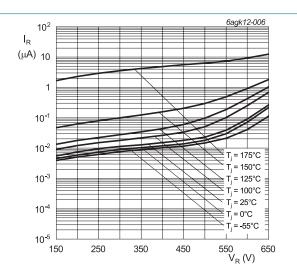


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value

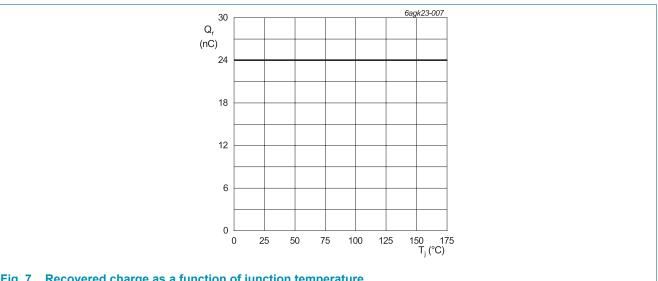
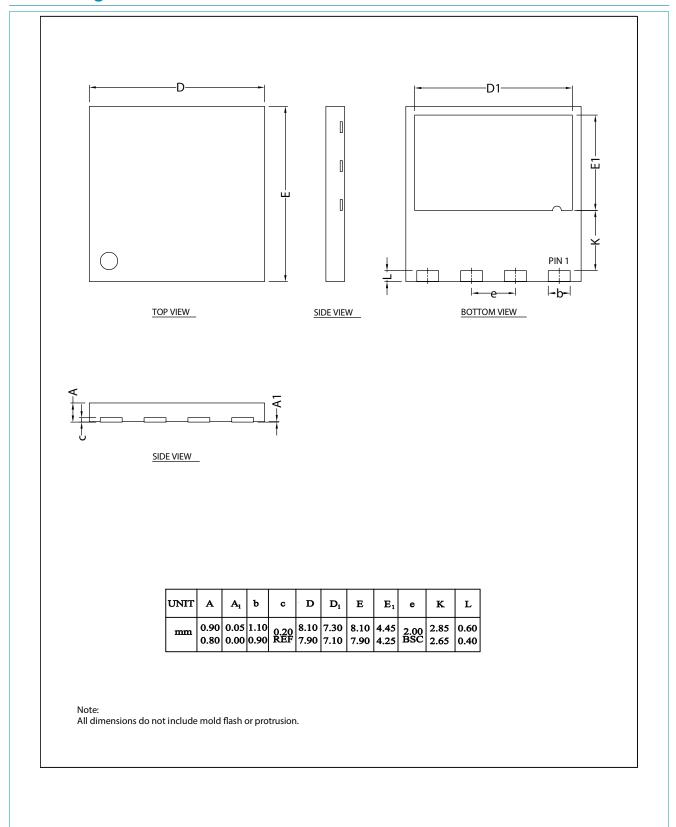


Fig. 7. Recovered charge as a function of junction temperature

# 11. Package outline



## 12. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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